
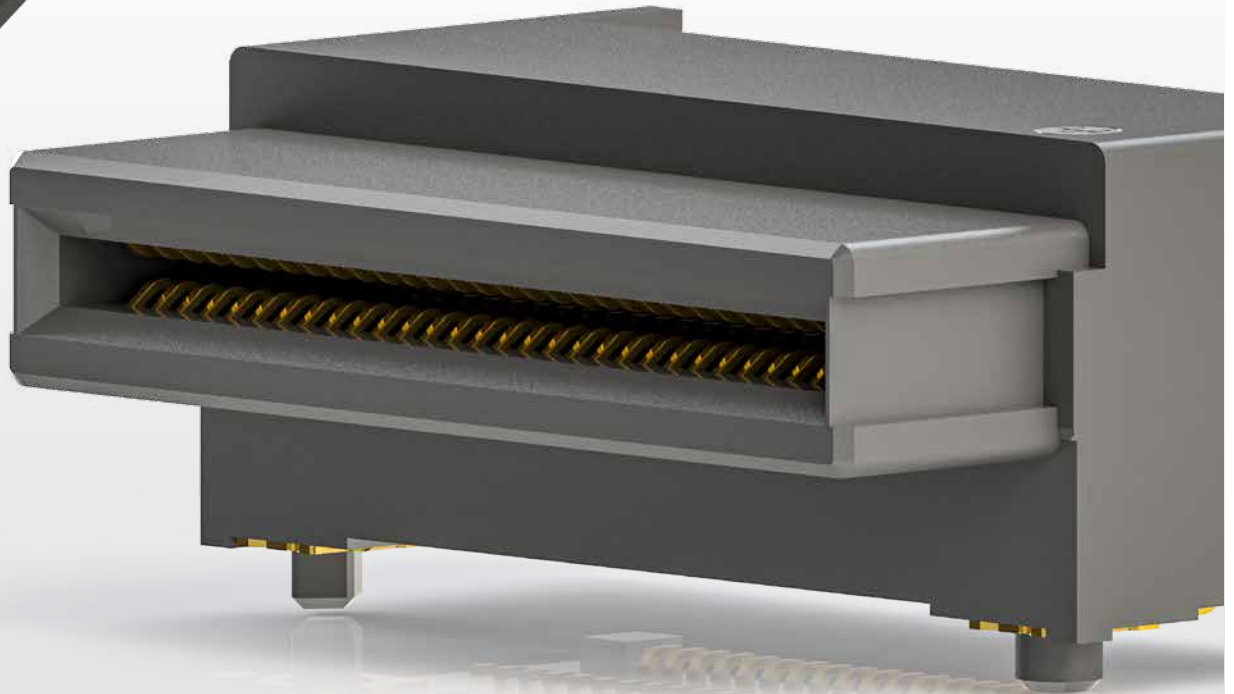
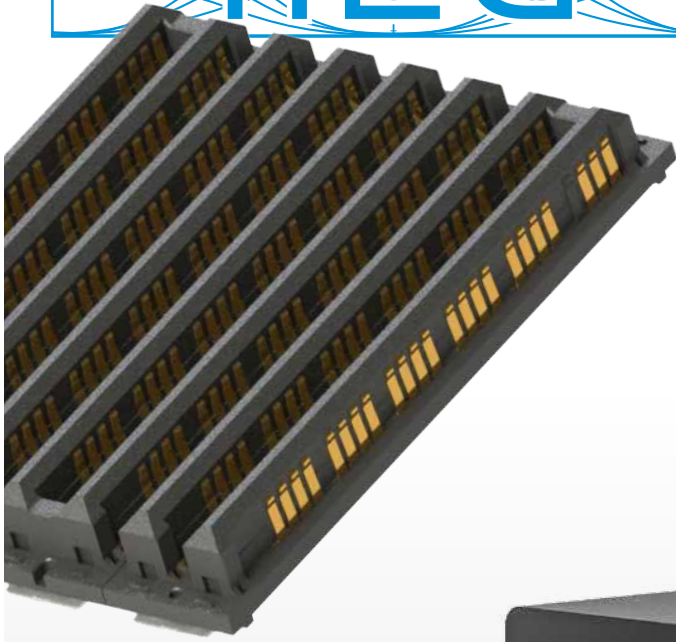


112G

 **YAMAICHI**
ELECTRONICS
ENGINEERED TO CONNECT



112Gbps CONNECTIVITY
SOLUTIONS

PLUGGABLE

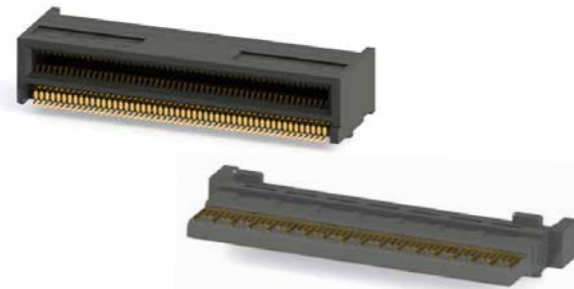
CFP 112

- Up to 112Gbps PAM4/64Gbps-NRZ per differential pair
- Capacity up to 2.2A for latest generation of DCO
- Connector, plug and mechanical sets available
- Custom-made cages and heat sinks with heat pipes for better heat dissipation or reduced dimension
- Supports Belly-to-Belly design
- Single and Dual-Port designs



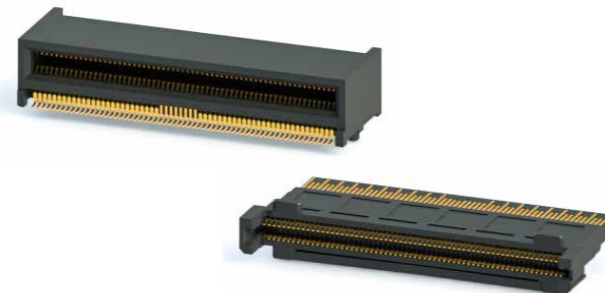
CFP2 112

- Up to 112Gbps PAM4/64Gbps-NRZ per differential pair
- Capacity up to 2.2A for latest generation of DCO
- Connector, plug and mechanical sets available
- Custom-made cages and heat sinks with heat pipes for better heat dissipation or reduced dimension
- Supports Belly-to-Belly design
- Single and Dual-Port designs



CFP8

- Up to 112Gbps PAM4/64Gbps-NRZ per differential pair
- Connector, plug and mechanical sets available
- Custom-made cages and heat sinks with heat pipes for better heat dissipation or reduced dimension
- Supports Belly-to-Belly design
- Single and Dual-Port designs



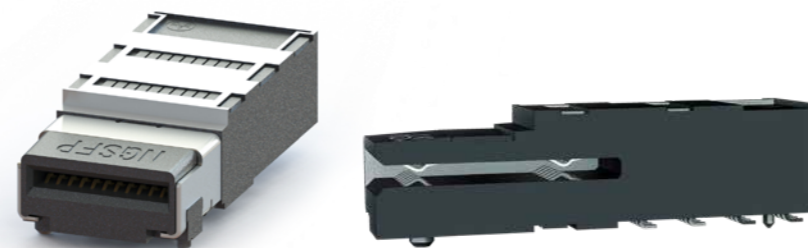
SFP 112/DSFP 112

- For SFP: 1 channel x 112Gbps
- For DSFP: 2 x 112Gbps/ch, up to 200GbE per slot – same size as SFP but 2 channels
- For DSFP 112: Double channel vs. single channel when compared to SFP
- For both: 56Gbps NRZ and 112Gbps PAM-4 per diff. pair
- For DSFP: Same outer dimension as SFP
- For DSFP: SFP area size compatibility (same occupied area on the board)
- For DSFP: SFP mechanical parts compatibility (all custom-made mechanical parts can be used)
- For SFP 112: 112Gbps performance for old footprint (SFP28) and new footprint (Subgroup of SFP-DD MSA)*



NGSFP-DD

- 4 channels x 112Gbps, 400GbE per slot
- Mating compatible to SFP & DSFP modules
- Double density = 2 DSFP contact rows



QSFP 112

- For style A (SFF-8662) style B (SFF-8672) upon request
- Industry leading signal integrity (SI report on request)
- Up to 56Gbps-NRZ or 112G-PAM4 per diff. pair
- Large variety of style A & style B cages and heat sink heights
- Widely applied for 100/200/400 GbE & InfiniBand EDR/FDR/QDR/HDR
- 112Gbps performance for old footprint (QSFP28) and new footprint (QSFP112 MSA)*



QSFP-DD800

- 1x1, 1x4, 2x1 and 2x6 cage configurations
- Fin- and Pin type heat sink available
- Industry leading signal integrity (SI report on request)
- Up to 112Gbps-PAM4 per diff. pair (1x1 type)
- Up to 56Gbps-PAM4 per diff. pair for 2x1 SMT stack type
- Wafer technology outperforming the market
- Allowing significantly higher power ratings per module than MSA spec
- 112Gbps performance for old footprint (QSFP-DD56) and new footprint (QSFP-DD800)*



OSFP 112

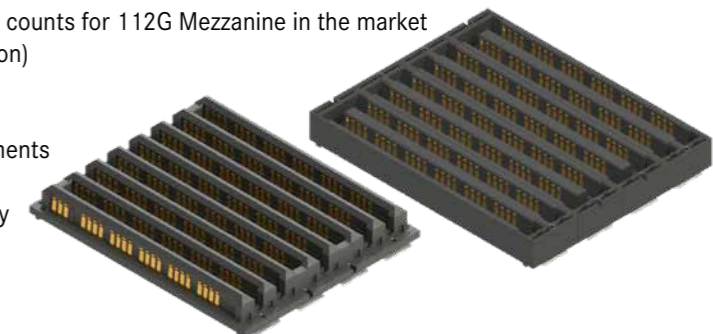
- 1x4, 2x1 and 2x4 cage configurations
- Single (1x1) and (2x1) host connector available
- Allowing significantly higher power ratings per module than MSA spec
- 224Gbps item under development



MEZZANINE

MEZZANINE CONNECTOR YTM-SERIES

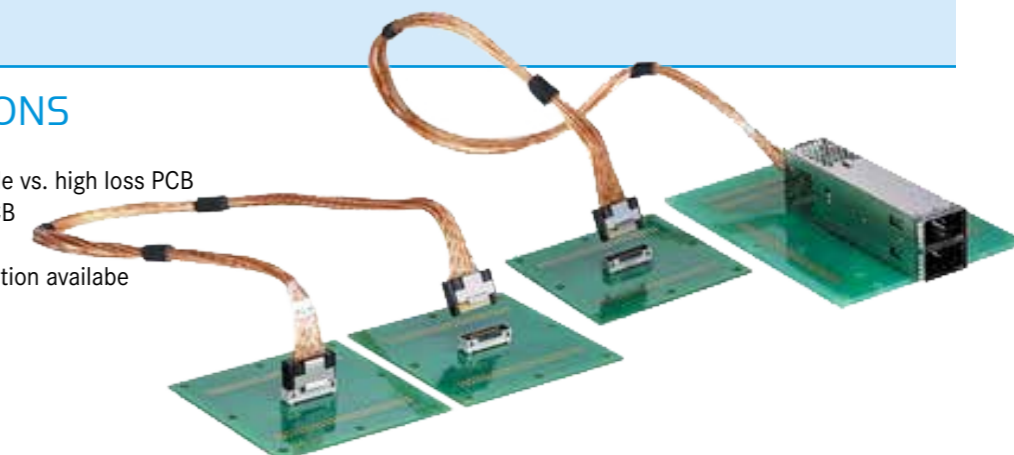
- Modular concept allowing widest variety of mating heights and pin counts for 112G Mezzanine in the market
- 96 pins per blade (picture is showing 8 blade/384pins configuration)
- 92Ohms (other impedance possible)
- 112Gbps-PAM4 on all differential pairs
- Mating height with plug and socket: 5mm to 10mm in 1mm increments
- Height extension by Interposer: 11mm up to max 40mm
- Genderless design with two point contacts for a better connectivity
- Various pin counts: 192, 288, 384 up to 960 pins
- Differential signal pairs up to 240 pairs (GSSG)



CABLE SOLUTIONS

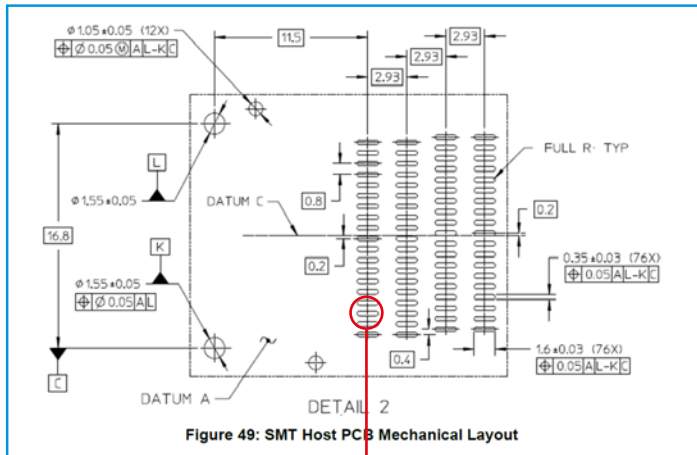
JUMPER CABLE SOLUTIONS

- Extended signal reach by low loss cable vs. high loss PCB
- Simplifies the design of high-speed PCB
- Relaxes the spec of the PCB material
- board to board and board to cage solution available

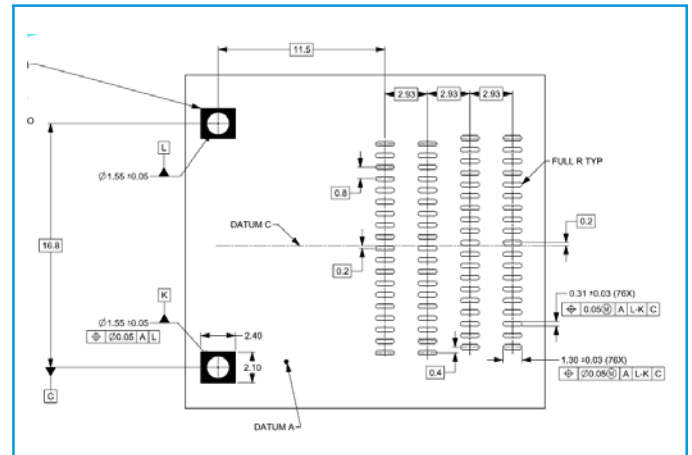


MACHINING DIMENSIONS OF HOST BOARD FOR QSFP-DD

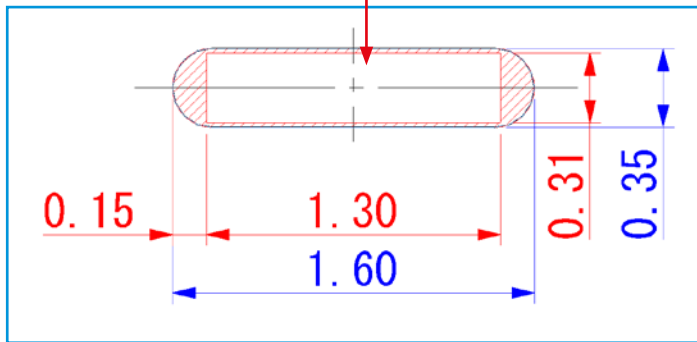
OLD FOOTPRINT REV.5.1 (FOR 400Gbps)



NEW FOOTPRINT REV.5.2.5 DRAFT (FOR 800Gbps)



MACHINING LOCATION / DIMENSIONS



Blue dimension: Pad dimension for 400Gbps

Red dimension: Pad dimension for 800Gbps

Perform additional machining on the red part of the Signal pad with the red dimension.

SFP AND QSFP:

For 112Gbps Performance old Footprint vs. new footprint please contact us!

112G CONNECTIVITY SOLUTIONS

Version June 2022

The specifications are subject to change without notice.

YAMAICHI ELECTRONICS

Deutschland GmbH
Concor Park
Bahnhofstraße 20
85609 Aschheim-Dornach
Germany

Phone +49 (0)89 45109-0
Fax +49 (0)89 45109-110
E-Mail sales@yamaichi.de
Web www.yamaichi.de

YAMAICHI ELECTRONICS

Italia s.r.l.
Centro Direzionale Colleoni
Via Colleoni, 1
Palazzo Taurus Ing. 1
20864 Agrate Brianza (MB)
Italy

Phone +39 039 6881-185
Fax +39 039 6892-150
E-Mail sales@yamaichi.it
Web www.yamaichi.it

YAMAICHI ELECTRONICS

GB Ltd.
6 The Clockhouse
Stratton Park
Micheldever
Hampshire SO21 3DP
Great Britain

Phone +44 (0)7808 493377
Fax +44 (0)1962 774902
E-Mail sales@yamaichi.co.uk
Web www.yamaichi.co.uk

YAMAICHI ELECTRONICS

Israel
P.O. # 66
Palmachim 7689000
Israel

Phone +972 54 20444 23
Fax +972 88 664 344
E-Mail sales@yamaichi.co.il
Web www.yamaichi.co.il